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# ZXTD4591AM832

## MPPS™ Miniature Package Power Solutions

### Complementary dual 40V high performance transistor

#### Summary

NPN Transistor -  $V_{CEO} = 40V$ ;  $R_{SAT} = 195m\Omega$ ;  $I_C = 2.5A$

PNP Transistor -  $V_{CEO} = -40V$ ;  $R_{SAT} = 350m\Omega$ ;  $I_C = -2A$

#### Description

Packaged in the 3mm x 2mm MLP (Micro Leaded Package), these high performance NPN / PNP combination dual transistors offer lower on state losses making them ideal for use in DC-DC circuits and various driving and power-management functions.

Users will also gain several other key benefits:

- Performance capability equivalent to much larger packages
- Improved circuit efficiency & power levels
- PCB area and device placement savings
- Lower package height (0.9mm nom)
- Reduced component count

#### Features

- Low Saturation Voltage (500mV max @1A)
- $H_{FE}$  specified up to 2A
- $I_C = 2.5A$  Continuous Collector Current
- 3mm x 2mm MLP

#### Applications

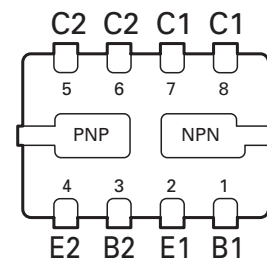
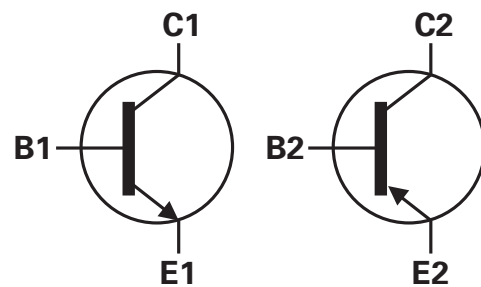
- DC - DC Converters
- Power switches
- Motor control
- LED Backlighting circuits

#### Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTD4591AM832TA	7	8	3,000
ZXTD4591AM832TC	13	8	10,000

#### Device marking

91A



Bottom view

# ZXTD4591AM832

## Absolute maximum ratings

Parameter	Symbol	NPN	PNP	Unit
Collector-Base voltage	$V_{CBO}$	40	-40	V
Collector-Emitter voltage	$V_{CEO}$	40	-40	V
Emitter-Base voltage	$V_{EBO}$	5	-5	V
Peak pulse current	$I_{CM}$	3	-3	A
Continuous collector current <sup>(a)(f)</sup>	$I_C$	2	-1.5	A
Continuous collector current <sup>(b)(f)</sup>	$I_C$	2.5	-2.0	A
Base current	$I_B$	300		mA
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(a)(f)</sup>	$P_D$	1.5		W
Linear derating factor		12		mW/°C
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(b)(f)</sup>	$P_D$	2.45		W
Linear derating factor		19.6		mW/°C
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(c)(f)</sup>	$P_D$	1		W
Linear derating factor		8		mW/°C
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(d)(f)</sup>	$P_D$	1.13		W
Linear derating factor		9		mW/°C
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(d)(g)</sup>	$P_D$	1.7		W
Linear derating factor		13.6		mW/°C
Power dissipation at $T_A = 25^\circ\text{C}$ <sup>(e)(g)</sup>	$P_D$	3		W
Linear derating factor		24		mW/°C
Storage temperature range	$T_{stg}$	-55 to +150		°C
Junction temperature range	$T_j$	150		°C

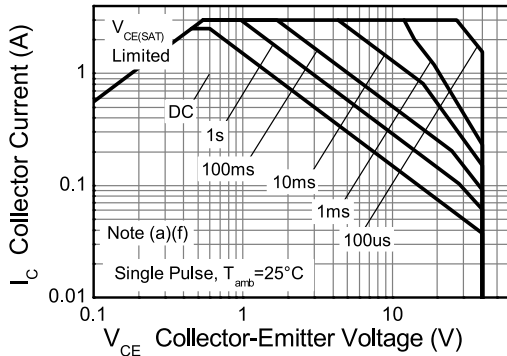
## Thermal resistance

Parameter	Symbol	Value	Unit
Junction to ambient <sup>(a)(f)</sup>	$R_{\theta JA}$	83.3	°C/W
Junction to ambient <sup>(b)(f)</sup>	$R_{\theta JA}$	51	°C/W
Junction to ambient <sup>(c)(f)</sup>	$R_{\theta JA}$	125	°C/W
Junction to ambient <sup>(d)(f)</sup>	$R_{\theta JA}$	111	°C/W
Junction to ambient <sup>(d)(g)</sup>	$R_{\theta JA}$	73.5	°C/W
Junction to ambient <sup>(e)(g)</sup>	$R_{\theta JA}$	41.7	°C/W

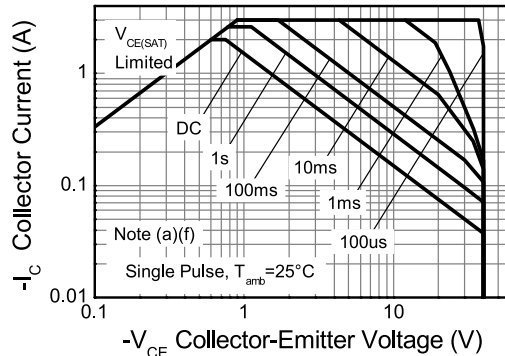
### NOTES:

- (a) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (b) Measured at  $t < 5$  secs for a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (c) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with minimal lead connections only**.
- (d) For a dual device surface mounted on 10 sq cm single sided 1oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (e) For a dual device surface mounted on 85 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (f) For a dual device with one active die.
- (g) For dual device with 2 active die running at equal power.
- (h) Repetitive rating - pulse width limited by max junction temperature. Refer to Transient Thermal Impedance graph.
- (i) The minimum copper dimensions required for mounting are no smaller than the exposed metal pads on the base of the device as shown in the package dimensions data. The thermal resistance for a dual device mounted on 1.5mm thick FR4 board using minimum copper 1 oz weight, 1mm wide tracks and one half of the device active is  $R_{th} = 250^\circ\text{C/W}$  giving a power rating of  $P_{tot} = 500\text{mW}$ .

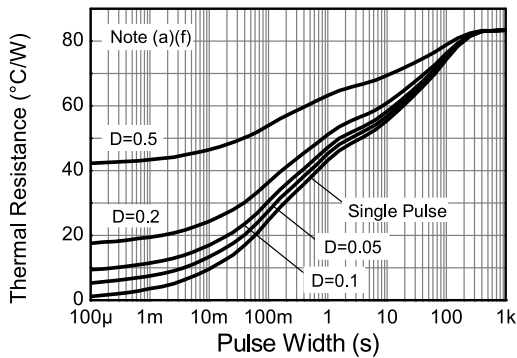
## Typical characteristics



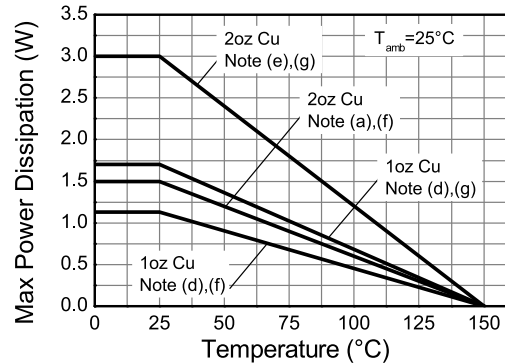
**NPN Safe Operating Area**



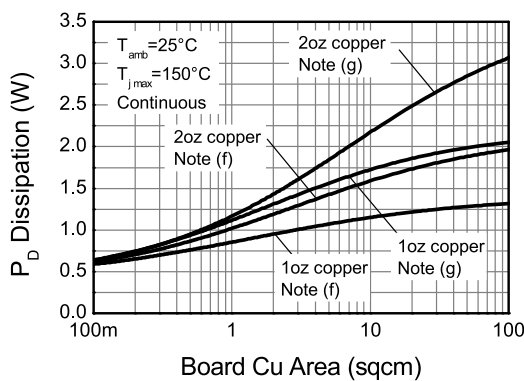
**PNP Safe Operating Area**



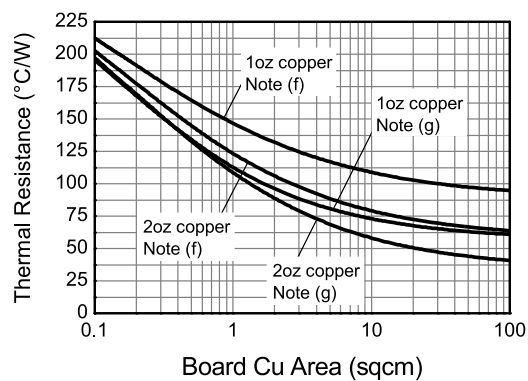
**Transient Thermal Impedance**



**Derating Curve**



**Power Dissipation v Board Area**



**Thermal Resistance v Board Area**

# ZXTD4591AM832

## NPN Transistor

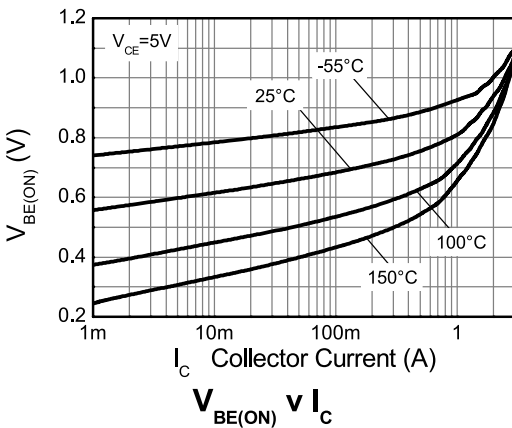
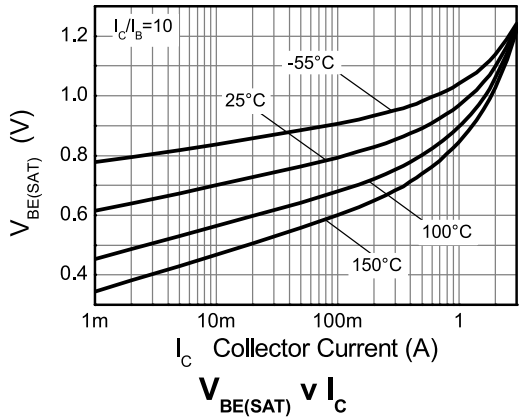
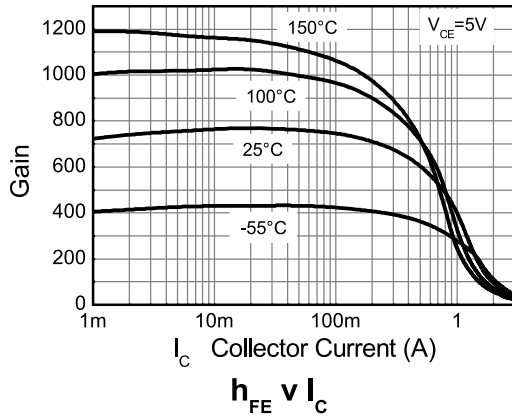
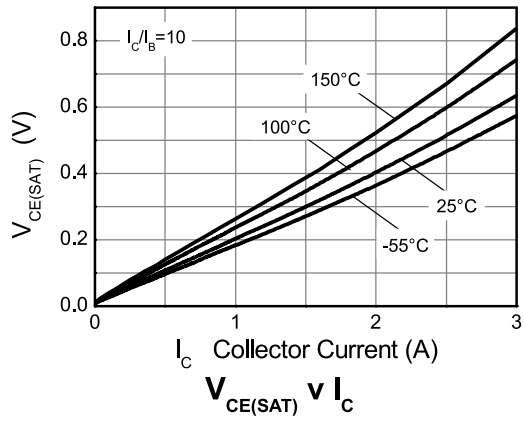
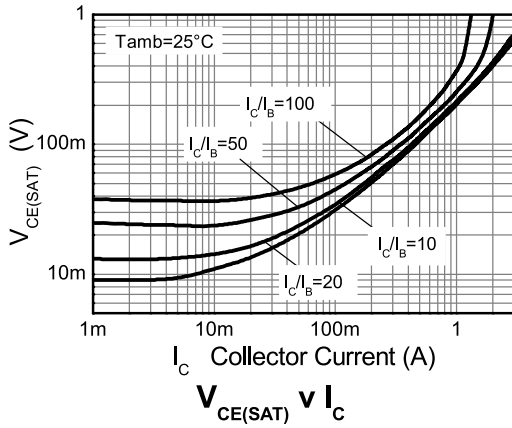
**Electrical characteristics** (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-Base breakdown voltage	$V_{(BR)CBO}$	40			V	$I_C = 100\mu\text{A}$
Collector-Emitter breakdown voltage	$V_{(BR)CEO}$	40			V	$I_C = 10\text{mA}^{(*)}$
Emitter-Base breakdown voltage	$V_{(BR)EBO}$	5			V	$I_E = 100\mu\text{A}$
Collector cut-off current	$I_{CBO}$			100	nA	$V_{CB} = 30\text{V}$
Emitter cut-off current	$I_{EBO}$			100	nA	$V_{EB} = 4\text{V}$
Collector Emitter cut-off current	$I_{CES}$			100	nV	$V_{CE} = 30\text{V}$
Collector Emitter saturation voltage	$V_{CE(sat)}$			300 500	mV mV	$I_C = 0.5\text{A}, I_B = 50\text{mA}^{(*)}$ $I_C = 1\text{A}, I_B = 100\text{mA}^{(*)}$
Base-Emitter saturation voltage	$V_{BE(sat)}$			1.1	V	$I_C = 1\text{A}, I_B = 100\text{mA}^{(*)}$
Base-Emitter turn-on voltage	$V_{BE(on)}$			1.0	V	$I_C = 1\text{A}, V_{CE} = 5\text{V}^{(*)}$
Static forward current transfer ratio	$h_{FE}$	300 300 200 35		900		$I_C = 1\text{mA}, V_{CE} = 5\text{V}^{(*)}$ $I_C = 0.5\text{A}, V_{CE} = 5\text{V}^{(*)}$ $I_C = 1\text{A}, V_{CE} = 5\text{V}^{(*)}$ $I_C = 2\text{A}, V_{CE} = 5\text{V}^{(*)}$
Transition frequency	$f_T$	150			MHz	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$ $f = 100\text{MHz}$
Output capacitance	$C_{OBO}$			10	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$

**NOTES:**

(\*) Measured under pulsed conditions.

## NPN Typical characteristics



# ZXTD4591AM832

## PNP Transistor

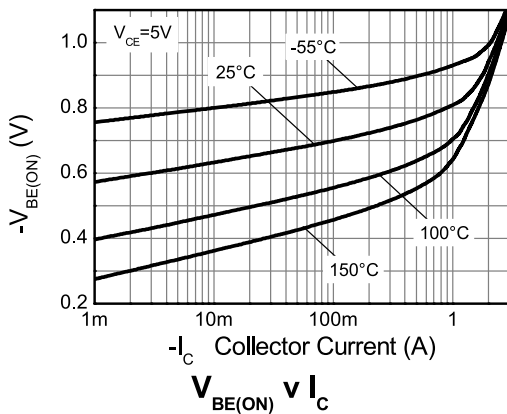
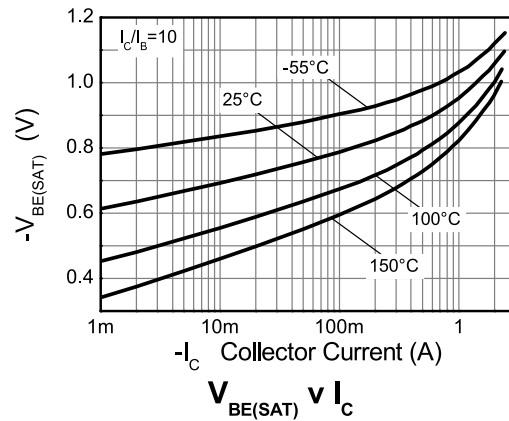
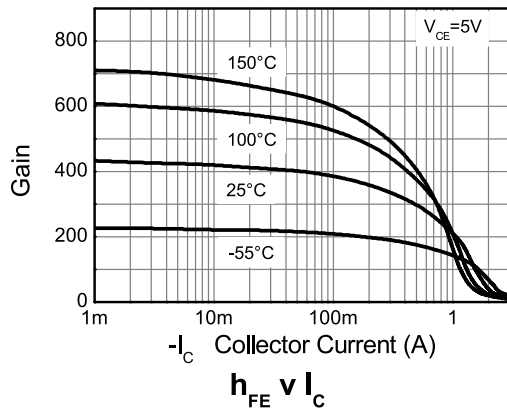
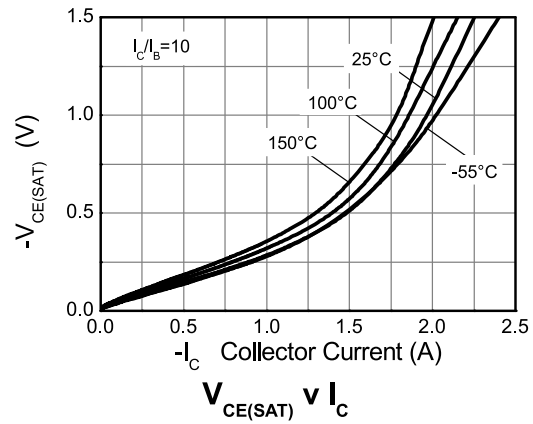
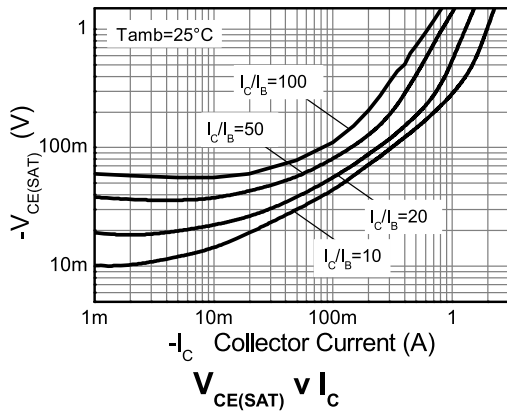
**Electrical characteristics** (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-Base breakdown voltage	$V_{(BR)CBO}$	-40			V	$I_C = -100\mu\text{A}$
Collector-Emitter breakdown voltage	$V_{(BR)CEO}$	-40			V	$I_C = -10\text{mA}^{(*)}$
Emitter-Base breakdown voltage	$V_{(BR)EBO}$	-5			V	$I_E = -100\mu\text{A}$
Collector cut-off current	$I_{CBO}$			-100	nA	$V_{CB} = -30\text{V}$
Emitter cut-off current	$I_{EBO}$			-100	nA	$V_{EB} = -4\text{V}$
Collector Emitter cut-off current	$I_{CES}$			-100	nV	$V_{CE} = -30\text{V}$
Collector Emitter saturation voltage	$V_{CE(sat)}$			-200 -350 -500	mV mV mV	$I_C = -0.1\text{A}, I_B = -1\text{mA}^{(*)}$ $I_C = -0.5\text{A}, I_B = -20\text{mA}^{(*)}$ $I_C = -1\text{A}, I_B = -100\text{mA}^{(*)}$
Base-Emitter saturation voltage	$V_{BE(sat)}$			-1.1	V	$I_C = -1\text{A}, I_B = -50\text{mA}^{(*)}$
Base-Emitter turn-on voltage	$V_{BE(on)}$			-1.0	V	$I_C = -1\text{A}, V_{CE} = -5\text{V}^{(*)}$
Static forward current transfer ratio	$h_{FE}$	300 300 250 160 30		800		$I_C = -1\text{mA}, V_{CE} = -5\text{V}^{(*)}$ $I_C = -0.1\text{A}, V_{CE} = -5\text{V}^{(*)}$ $I_C = -0.5\text{A}, V_{CE} = -5\text{V}^{(*)}$ $I_C = -1\text{A}, V_{CE} = -5\text{V}^{(*)}$ $I_C = -2\text{A}, V_{CE} = -5\text{V}^{(*)}$
Transition frequency	$f_T$	150			MHz	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$ $f = 100\text{MHz}$
Output capacitance	$C_{OBO}$			10	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$

**NOTES:**

(\*) Measured under pulsed conditions.

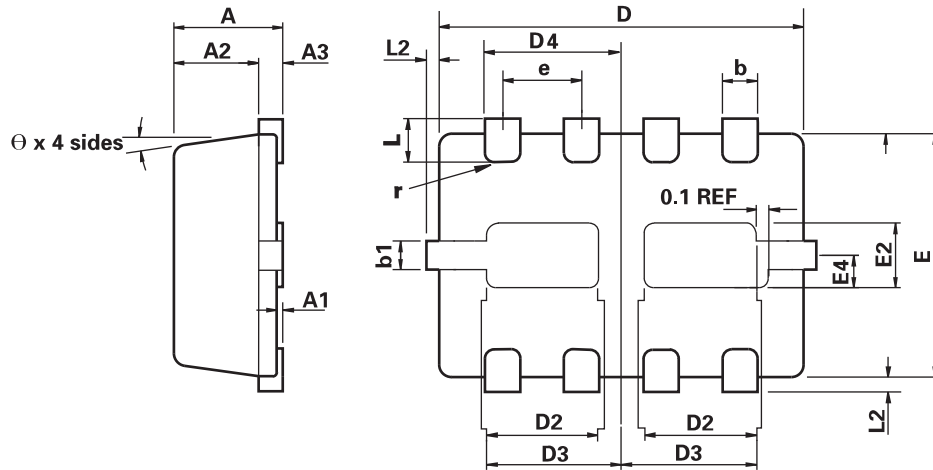
## PNP electrical characteristics





# ZXTD4591AM832

## Package outline MLP832



Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.80	1.00	0.0315	0.0394	e	0.65 BSC		0.0256 BSC	
A1	0.00	0.05	0.00	0.002	E	2.00 BSC		0.0787 BSC	
A2	0.65	0.75	0.0256	0.0295	E2	0.43	0.63	0.017	0.0248
A3	0.15	0.25	0.006	0.0098	E4	0.16	0.36	0.006	0.014
b	0.24	0.34	0.0095	0.0134	L	0.20	0.45	0.0079	0.0177
b1	0.17	0.30	0.0068	0.0118	L2	0.00	0.125	0.00	0.005
D	3.00 BSC		0.118 BSC		r	0.075 BSC		0.0029 BSC	
D2	0.82	1.02	0.0323	0.0402	θ	0°	12°	0°	12°
D3	1.01	1.21	0.0398	0.0476	-	-	-	-	-

**Note:** Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

**ZXTD4591AM832**

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or

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"Active"	Product status recommended for new designs
"Last time buy (LTB)"	Device will be discontinued and last time buy period and delivery is in effect
"Not recommended for new designs"	Device is still in production to support existing designs and production
"Obsolete"	Production has been discontinued

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